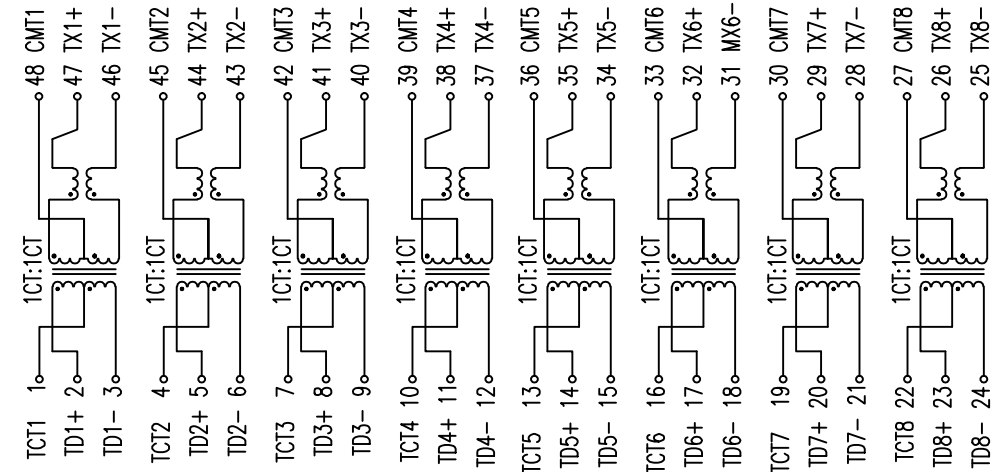
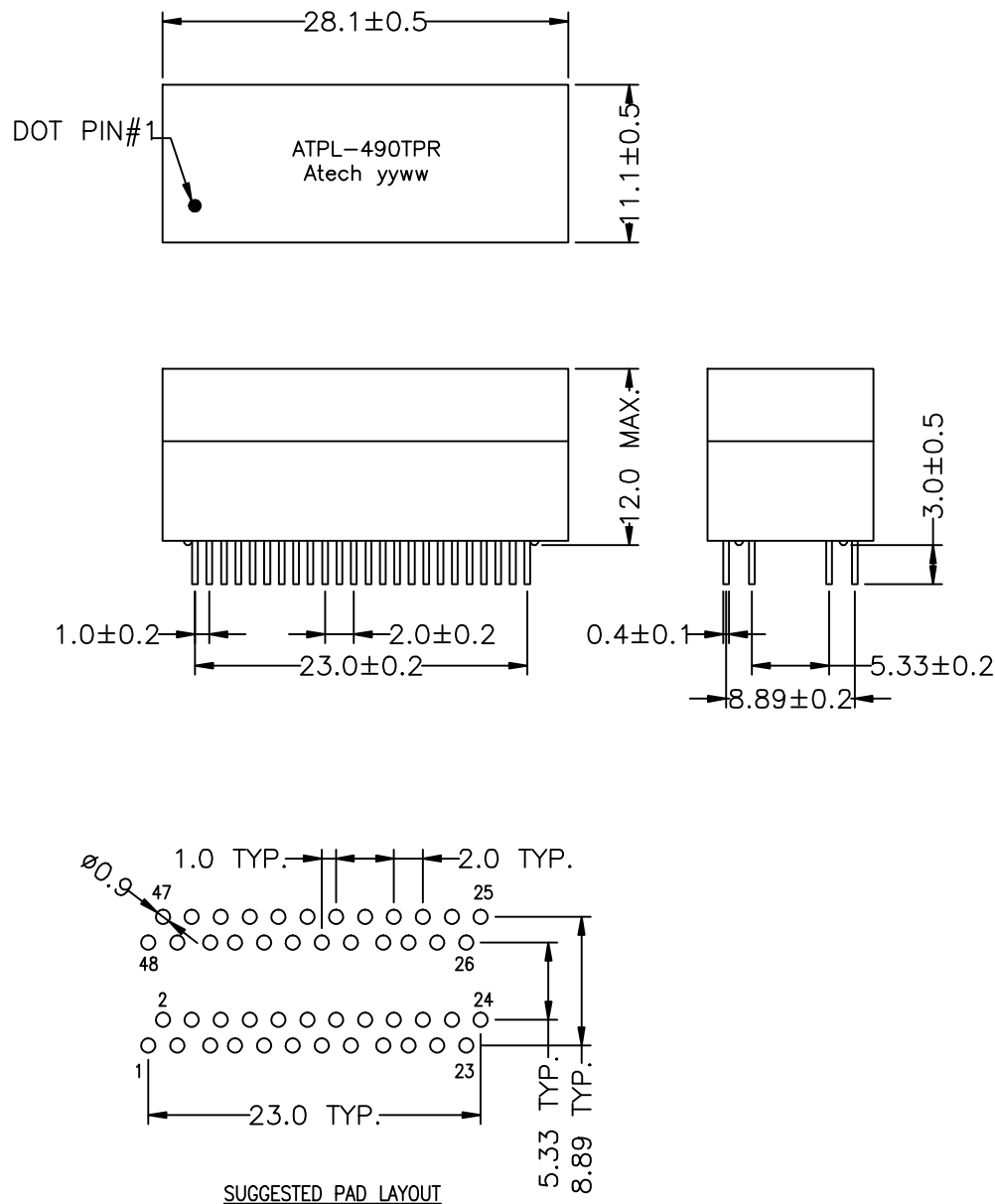


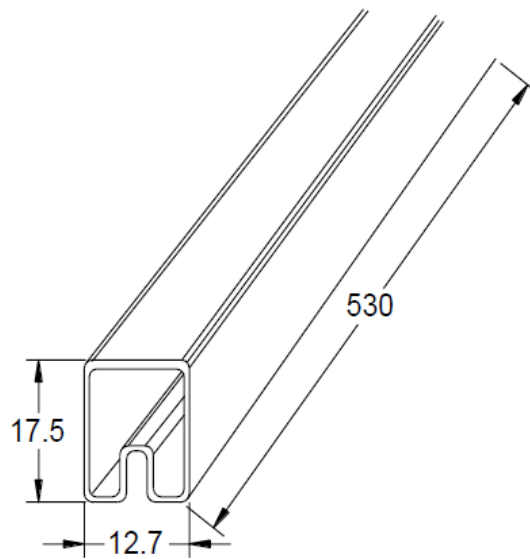


ELECTRICAL CHARACTERISTICS @25°C :

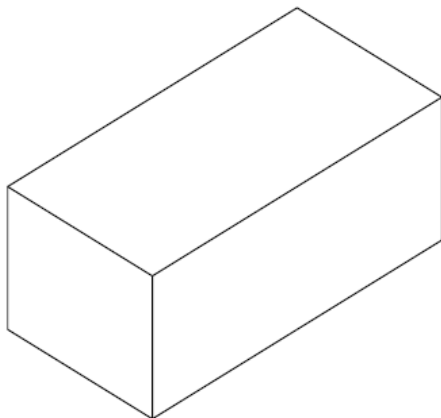
- INSULATION HI-POT(PRI./SEC.) : 1500Vrms, 1mA, 60SEC
- TURN RATIO (±5%) : TX = 1CT : 1CT
RX = 1CT : 1CT
- OCL : 350uH MIN. 100KHz/0.1V AT 8mA DC BIAS
- INSERTION LOSS : 1-100MHz = -1.1dB MAX.
- RETURN LOSS (dB MIN.) : 1-30MHz 40MHz 50MHz 60-80MHz 100MHz
-18 -14.4 -13.1 -12 -10
- CROSS TALK (dB MIN.) : 1-100MHz = -30dB MIN
- COMMON MODE REJECTION (dB MIN.) : 1-100MHz = -30dB MIN
- LEAKAGE INDUCTOR (100KHz, 0.1Vrms) : 0.5uH MAX.
- DCR : 1400mΩ MAX.
- PoE Support 30W : Each channel support 360mA DC balance current ,
Full channels support 720mA DC balance current.
- OPERATING TEMPERATURE : -40°C~+85°C
STORAGE TEMPERATURE : -40°C~+85°C

							TITLE 100/1000 BASE-T PoE TRANSFORMER DWG. NO. ATPL-490TPR	
RELEASE	08/27/2019	SHIRLEY	BETTY	BETTY			SHEET 1 of 1	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	UNITS: M/M	SAFETY	DRAW SHIRLEY
REVISIONS						DATE 08/27/19	P/N:	

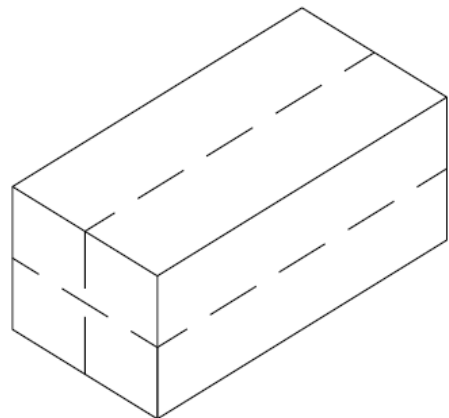
3. Package:



Tube: 530*12.7*17.5mm



Inner Carton: L570*W180*H100mm



Export Carton: L580*W380*H240mm

Package Quantity:

One Tube=18Pcs

One Inner Carton=18*50=900Pcs

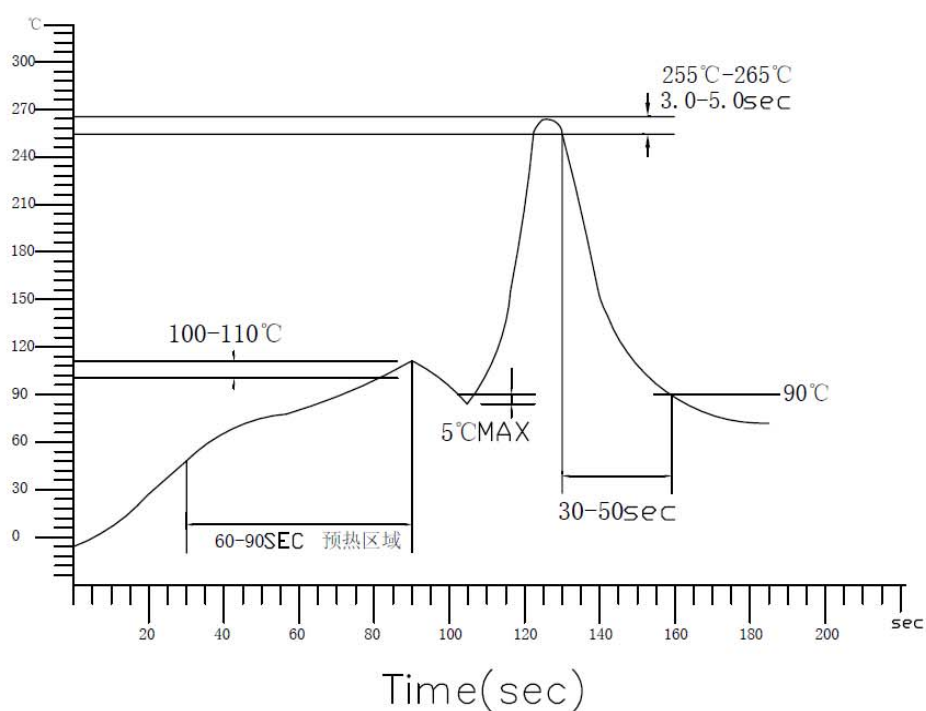
One Export Carton=900*4=3600Pcs

6. Soldering Heat Withstanding Survey (DIP)

Pb-free Soldering Heat Withstanding Survey(DIP)

Reflow conditions	Preheat area	Time at 220℃ or higher	Peak Temp	Holding time at 260℃ temp
Recommended conditions	Max 120s	Max 30s	260℃	Max 6S

Soldering Temp.profile



Soldering conditions	Soldering Temp.	Heating Time
Recommended conditions	260℃±5℃	Max 6 sec

Soldering Iron Conditions	Soldering Iron Temp	Heating Time
Recommended conditions	350±10℃	Max 5 sec

Part Electrode Plating Constitution	Sn.CU
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Any other series applicable same conditions	NO
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Packing Configuration	TRAY
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